

# LNJ326W83RA1

## Surface Mounting Chip LED

UTSS Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	40	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

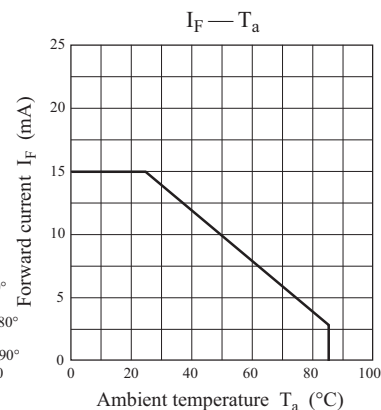
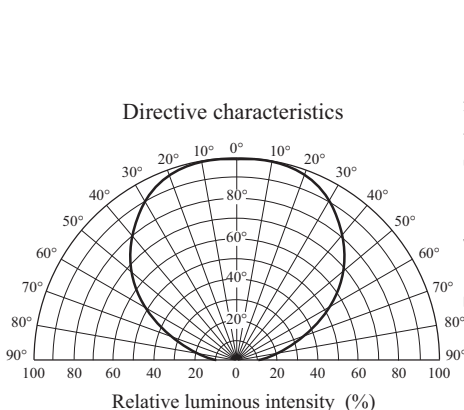
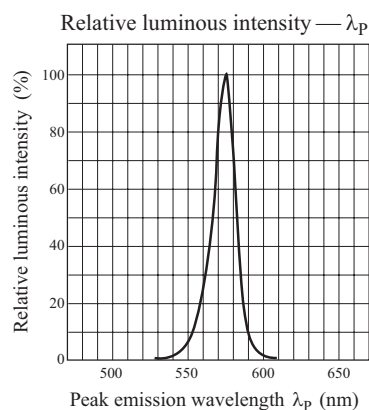
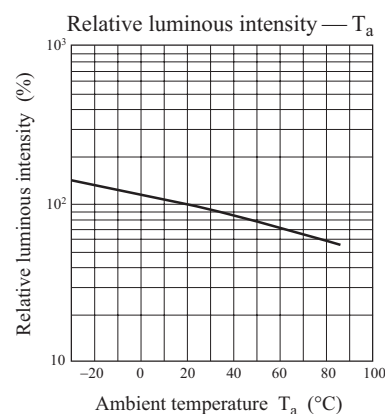
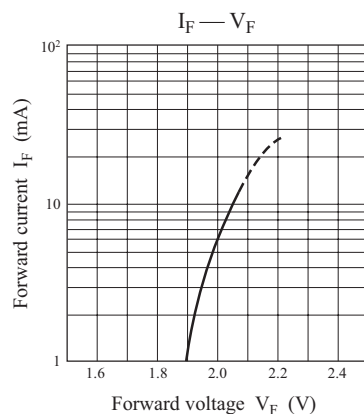
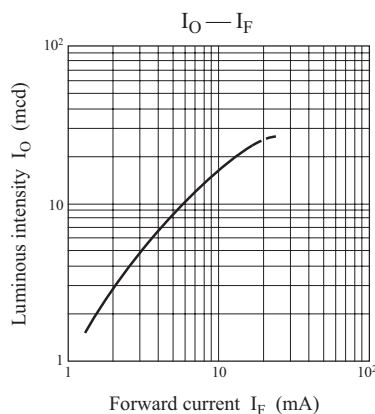
Note) \*: The condition of  $I_{FP}$  is duty 10%, pulse width 10 ms.

### ■ Lighting Color

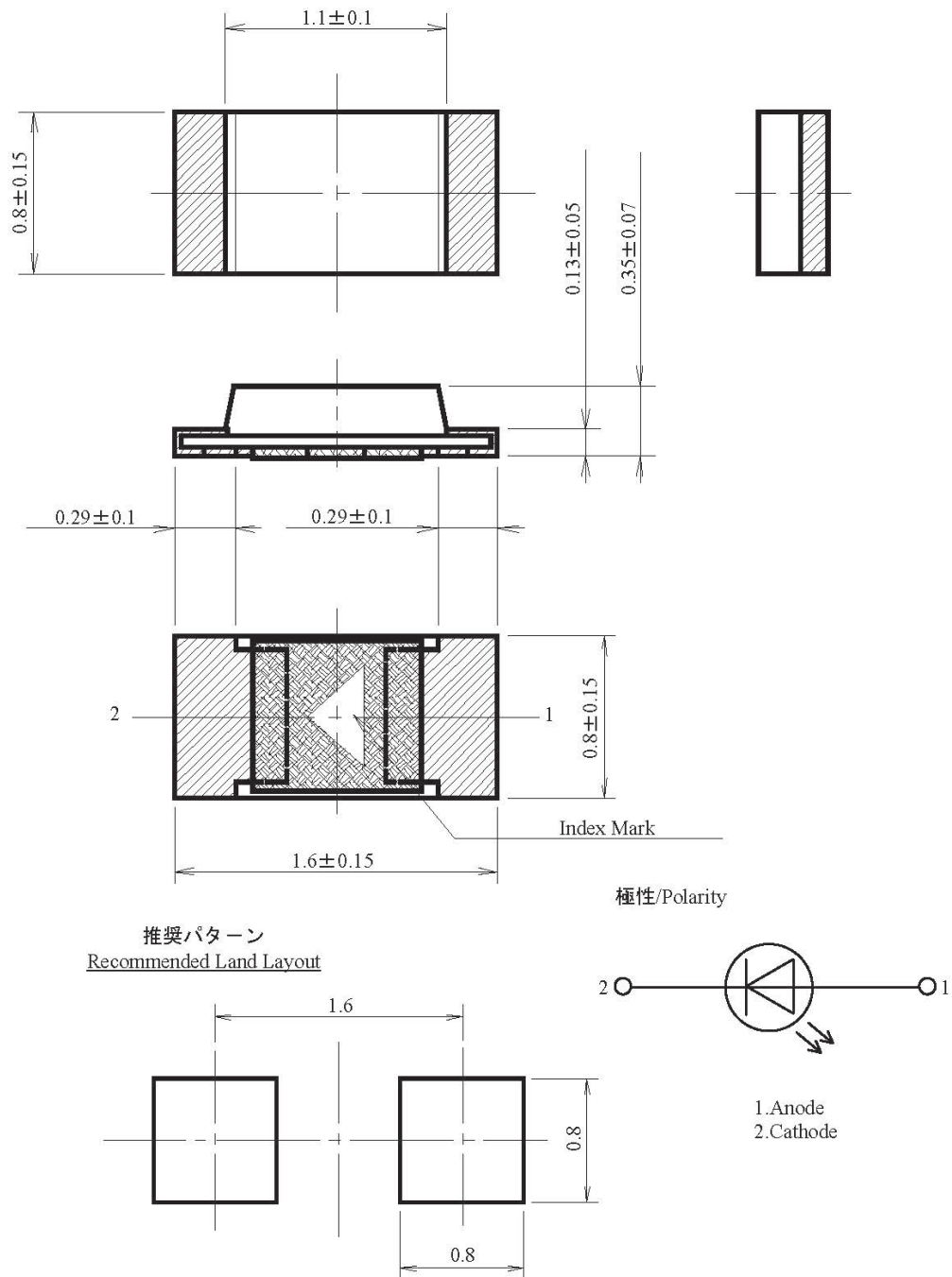
- Yellow Green

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$	$I_F = 10\text{ mA}$	14.0	18.0	50.0	mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.05	2.5	V
Peak emission wavelength	$\lambda_P$	$I_F = 10\text{ mA}$		575		nm
Dominant emission wavelength	$\lambda_d$	$I_F = 10\text{ mA}$	567.0	572.0	575.5	nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		15		nm

Note) \*1: Measurement tolerance:  $\pm 20\%$ \*2: Measurement tolerance:  $\pm 2\text{ nm}$ 

■ Package (Unit: mm)



注記/Notes

1. パッケージ寸法については電極バリを含まない。  
Measurement of the package doesn't include electrode projection.
2. 単位:mm/Unit : mm

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